



SUSS MICROTEC INVESTOR PRESENTATION

February 2016

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products & Markets

III. Financials

IV. Outlook

- + Global leader in manufacturing equipment for semiconductor devices
- + SUSS' Equipment creates micro structures that connect micro electronic devices
- + Focus on growth segments: advanced packaging, MEMS, and 2.5D / 3D Integration
- + Attractive end markets: smartphones, tablets, automotive, LED, sensors, IoT, ...

- + Sales FY 2015: €148.5 million
- + EBIT FY 2015: € 5.0 million (EBIT-margin: 3.4%)
- + Net Cash 2015: € 40.0 million
- + Market Cap 12/30/2015: € 160 million

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 27.6 € million
Sales 28.0 € million
Employees 116

EMEA

Order Entry 48.8 € million
Sales 40.5 € million
Employees 448

ASIA

Order Entry 112.2 € million
Sales 80.0 € million
Employees 134



*Figures refer to the fiscal year 2015

TABLE OF CONTENT



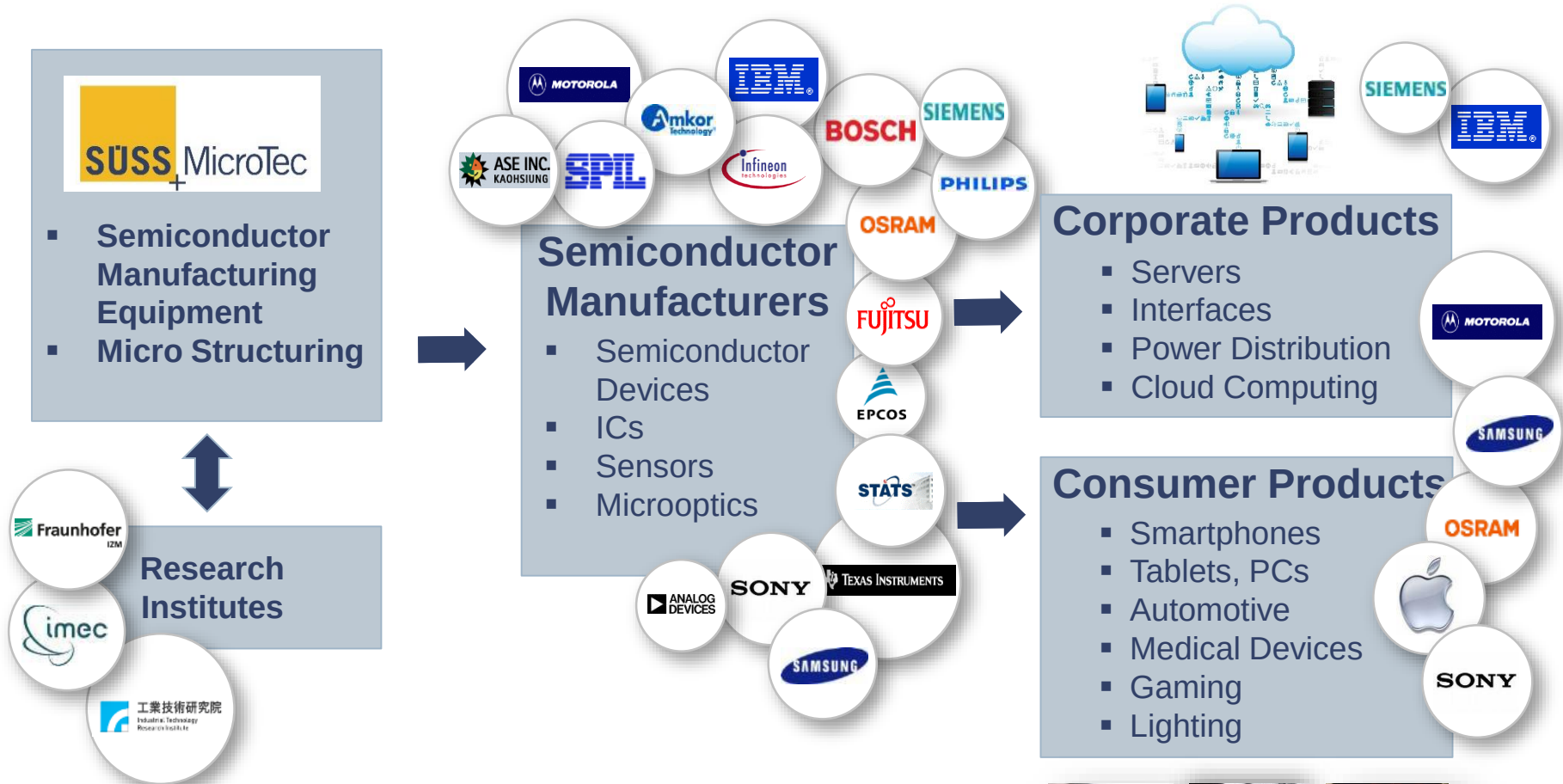
I. SUSS MicroTec at a Glance

II. Products & Markets

III. Financials

IV. Outlook

SUSS MICROTEC IN THE VALUE CHAIN

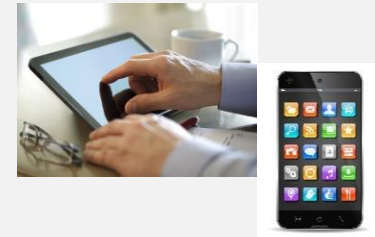


- + SUSS MicroTec:**
 - Key player in leading edge semiconductor manufacturing equipment
 - Developer of highly innovative process solutions
- + Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment**



Connectivity & Data Processing

- + Connection through apps, social media, data streaming
- + Connectivity of devices, Internet of Things (IoT)
- + Permanent internet connectivity provided by smartphones and tablet PCs at affordable cost
- + Industry 4.0 connectivity of manufacturing units



Mobility & Automotive

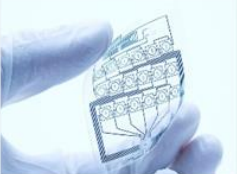
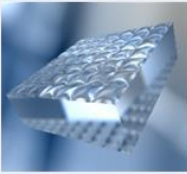
- + Autonomous, electric and plug in hybrid cars, E-Bikes, trains drive the need for power devices and high performance ICs at the same time
- + Growing electronic content and sensors (MEMS) for autonomous cars



Energy Efficiency

- + Environmental awareness and rising energy costs drive the demand for energy efficient devices
- + Energy efficiency in industrial production
- + Smart energy management in household applications
- + Green energy management systems



Semiconductors			Sensors	Lighting	Micro Optics
Front End Lithography ▪ Photomask Cleaning  	Advanced Packaging ▪ Micro-Bumping ▪ Fan-Out WLP ▪ Cu Pillar  	Chipset Integration ▪ 3D (TSV) Stacking ▪ 2.5D Integration  	MEMS ▪ Internet of Things ▪ Automotive ▪ Mobile Devices ▪ Industry 4.0 ▪ Biomedical  	LED ▪ General Lighting ▪ HB and UHB  	Advanced Optics ▪ Wafer Level Optics ▪ Fiber Optics ▪ Laser and Lithography Beam Shaping Optics   Micro Optical Components Micro lens arrays Diffractive optical elements



Frontend

Mid- and Backend

Photomask Equipment

Photomask Cleaning Equipment



MaskTrackPro

Lithography

Laser Processing Equipment



ELP300

Exposure Systems



Mask Aligner
MA200/300 Gen2



Projection Scanner
DSC300 Gen2

Coaters and Developers



ACS300 Gen2

Substrate Bonder

Wafer Bonding Equipment



XBC300 Gen2



XB8

Divisions

Photomask Equipment

Photomask Cleaning
Equipment

Order Entry: 21.5 € million
Sales: 23.5 € million
EBIT margin: 9.9%

Lithography

Laser
Processing
Equipment

Exposure
Systems

Coaters and
Developers

Order Entry: 149.6 € million
Sales: 106.3 € million
EBIT margin: 9.1%

Substrate Bonder

Wafer Bonding
Equipment

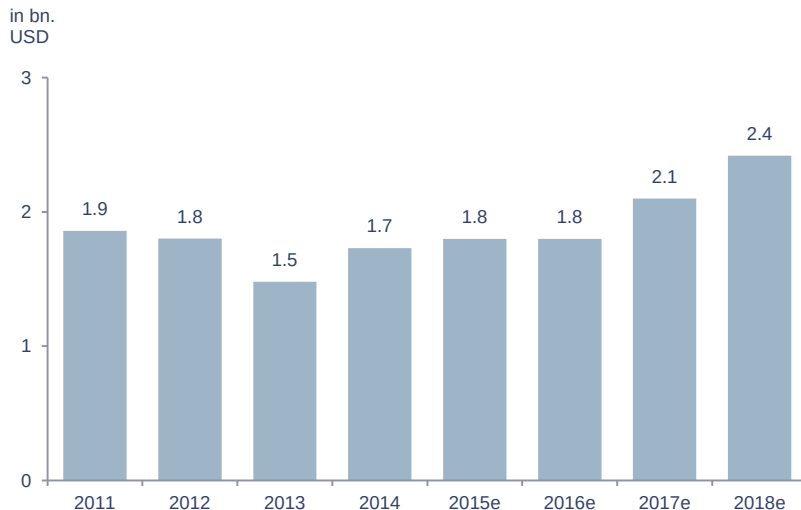
Order Entry: 10.5 € million
Sales: 11.4 € million
EBIT margin: -34.7%

**SUSS MicroTec Group
FY 2015**

Order Entry: 188.6 € million
Sales: 148.5 € million

EBIT: 5.0 € million
EBIT margin: 3.4%

Wafer-level packaging (WLP) and assembly equipment



Source: Gartner, January 2016

+ Attractive growth opportunities within wafer-level packaging:

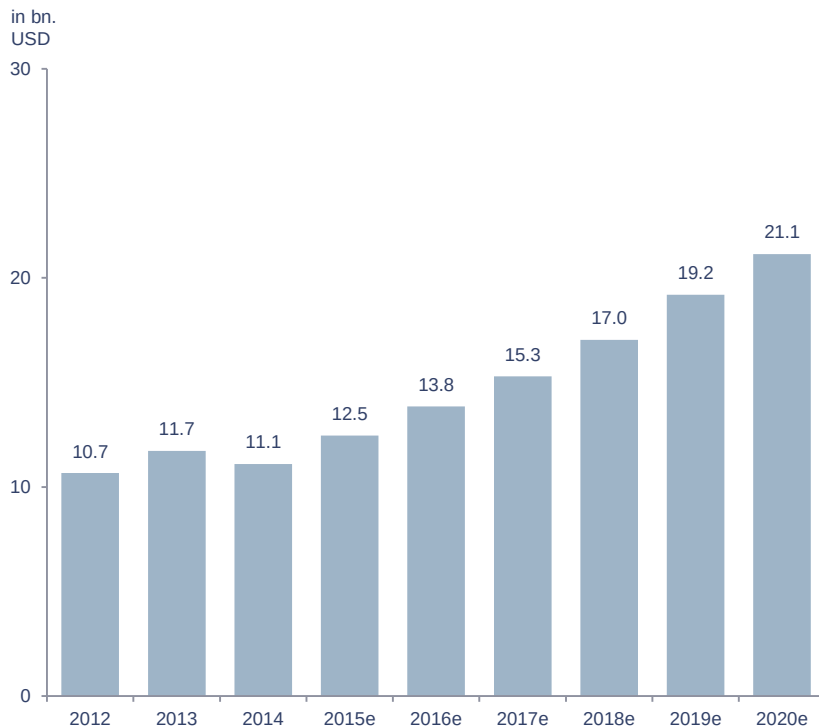
- Fan-out WLP
- Copper pillar
- Bumping

+ Grow market share for core products in advanced packaging: coater/developer, mask aligner

+ Achieve traction for new advanced lithography products from SUSS MicroTec Photonic Systems:

- Further HVM orders for scanner products
- Qualification of laser products at key customers

MEMS market



Source: Yole, May 2015

- + Internet of Things (IoT)
- + Smartphones and tablets
- + Automotive applications
- + Health/biomedical applications
- + Grow market share for core products for MEMS: coater/developer, mask aligner, substrate bonder
- + Market re-entry permanent bonder with new differentiated product

2D Packaging

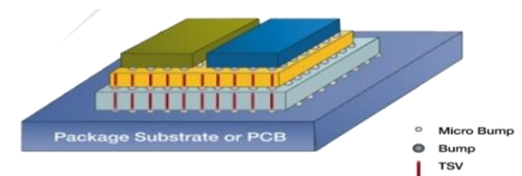
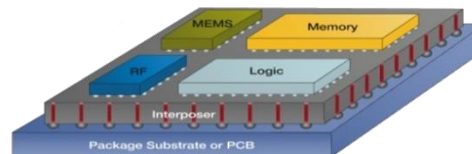
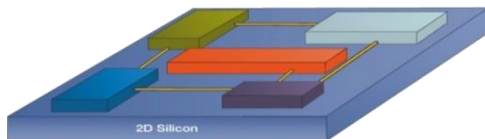
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning drive further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

2.5D Packaging

- Combining of several devices on an interposer addresses the limitations of traditional shrinking while enhancing performance
- Increased packaging density
- Reduced footprint
- Packaging becomes enabler and addresses performance slow down of Moore's Law

3D Integration (TSV)

- Stacking of several devices horizontally enables high performance at a low footprint
- TSV and bonded thin Si technology becomes key enabler for scaling
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 2.5D / 3D integration ("*More than Moore*")

TABLE OF CONTENT



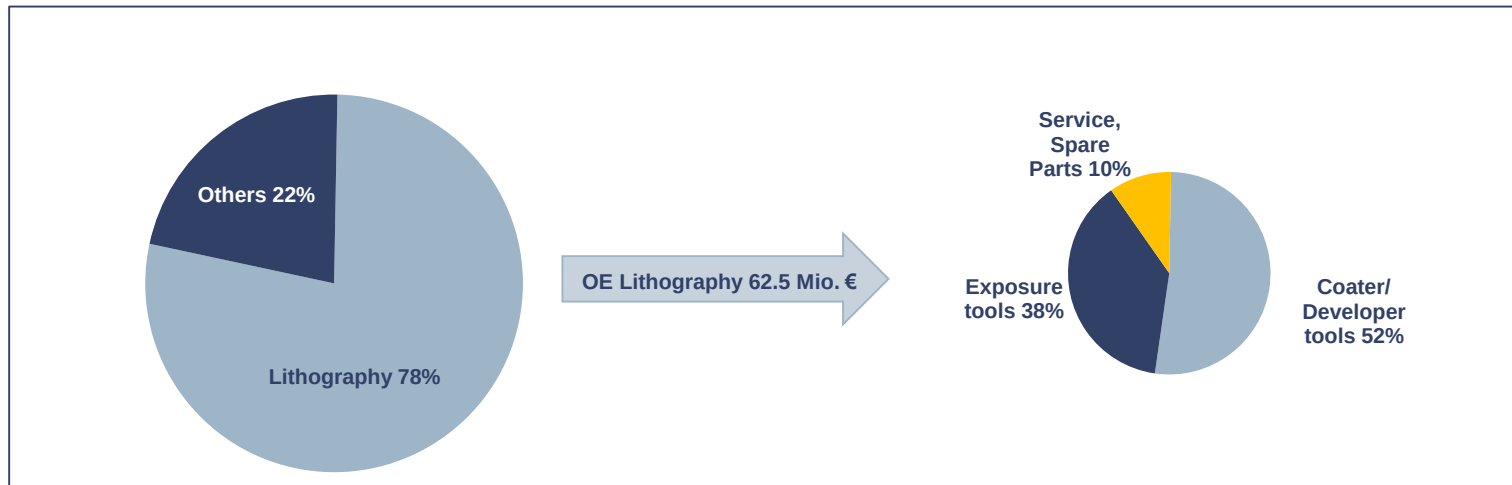
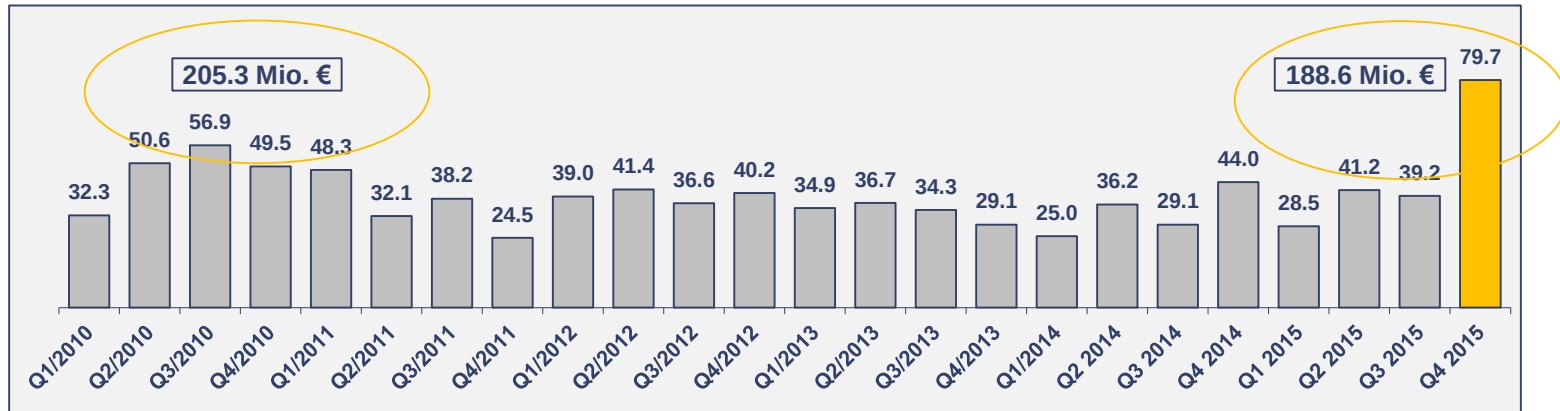
I. SUSS MicroTec at a Glance

II. Products & Markets

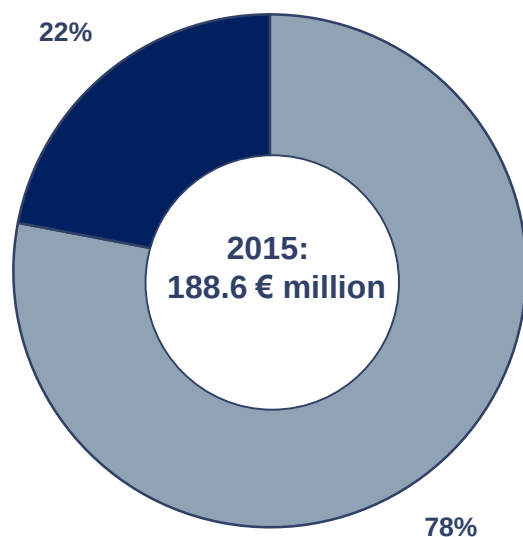
III. Financials

IV. Outlook

ORDER ENTRY Q4 2015 AT RECORD LEVEL

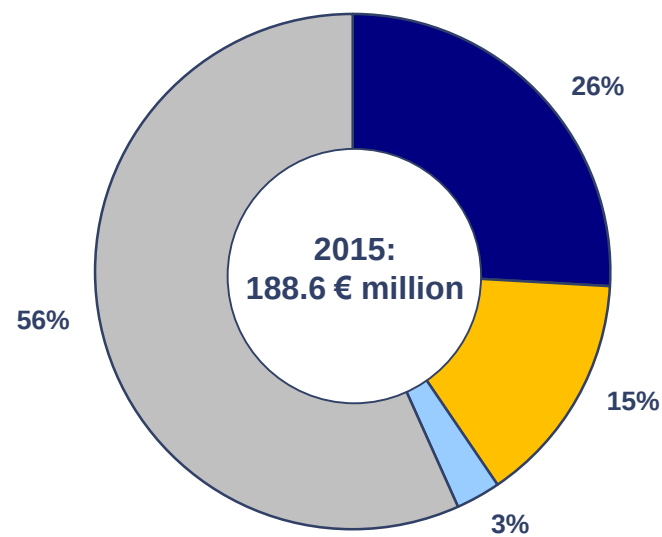


Order Entry by Segment



■ Lithography
■ Others

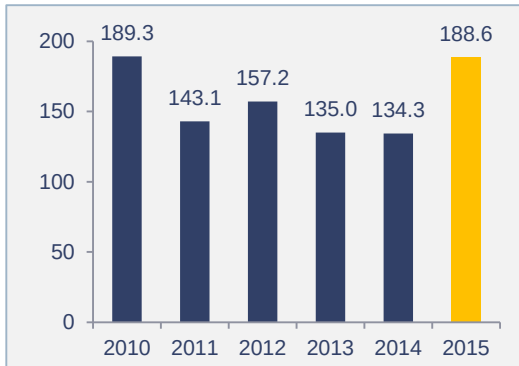
Order Entry by Region



■ Europe
■ North America
■ Japan
■ Rest of Asia

LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

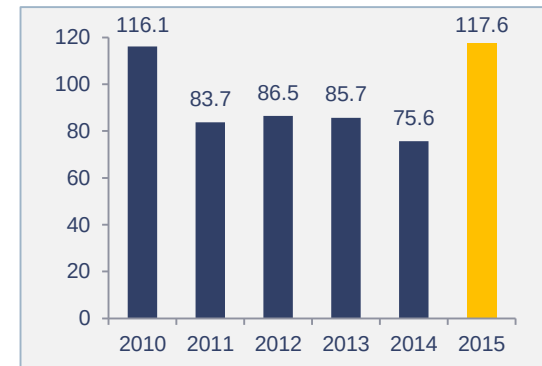
Order Entry in € million



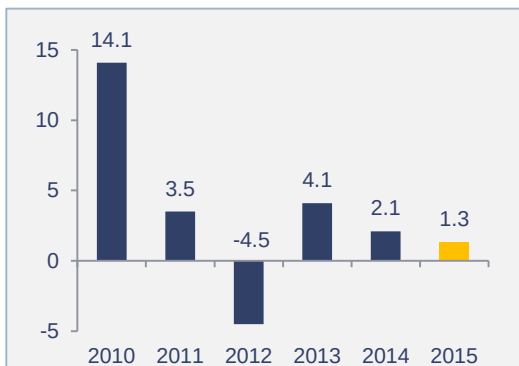
Sales in € million



Order Backlog in € million



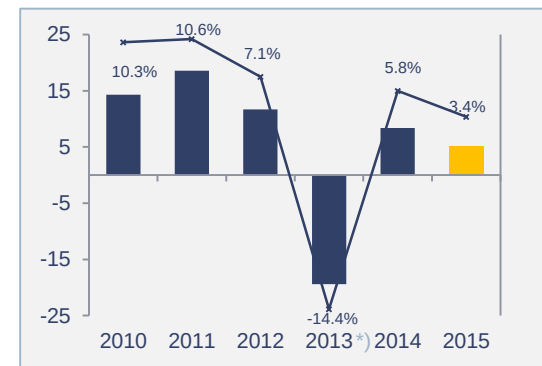
Free Cash Flow in € million



Net Cash in € million



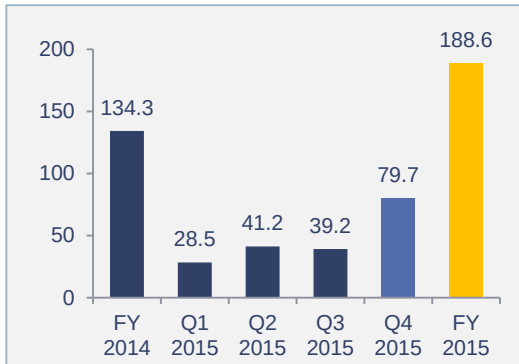
EBIT in € million



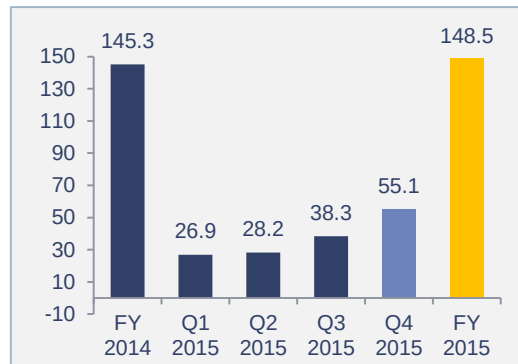
* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

2015 - P&L KEY FIGURES BY QUARTER

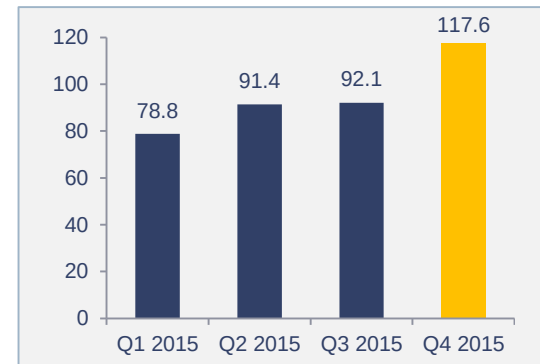
Order Entry in € million



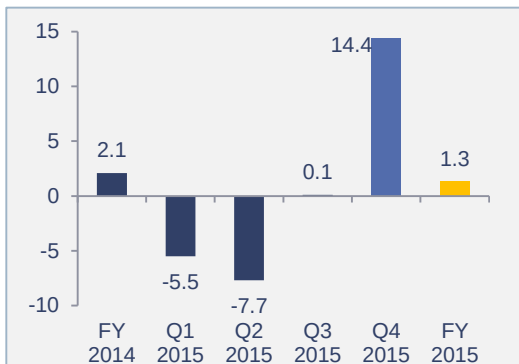
Sales in € million



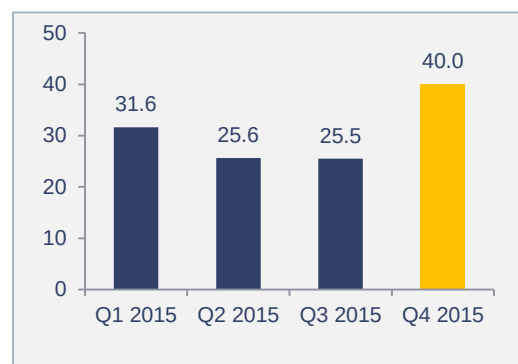
Order Backlog in € million



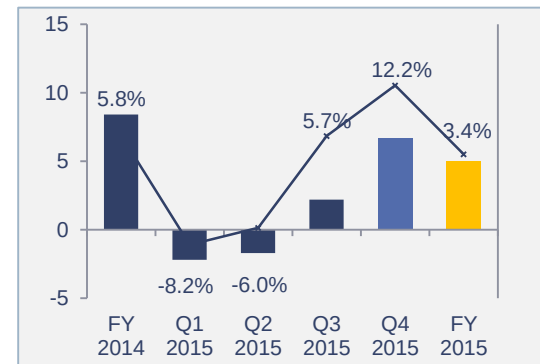
Free Cash Flow in € million



Net Cash in € million



EBIT in € million



in € million	2015	2014	in %
Order Intake	188.6	134.3	+40.4%
Order Backlog 12/31	117.6	75.6	+55.6%
Revenue	148.5	145.3	+2.2%
EBIT	5.0	8.4	-40.5%
<i>EBIT in % of Sales</i>	<i>3.4%</i>	<i>5.8%</i>	<i>-2.4%pt.</i>
Net Cash	40.0	38.0	+5.3%
Free Cash Flow*	1.3	2.1	-38.1%

* before consideration of purchased / sold interest-bearing securities

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products & Markets

III. Financials

IV. Outlook

Short-term

- + Grow market share for core products in all market segments
- + Traction for new advanced lithography products from SUSS MicroTec Photonic Systems
- + Stabilize Company at positive EBIT and cash generation, continue revenue growth:
 - Gross margin 30-35%

Mid-term

- + Focused product portfolio
- + Positive EBIT from Bonder Division and Photonic Systems
- + Successful new adjacent market entries (leverage existing technologies to grow SAM)
- + Continue revenue growth at positive EBIT and cash generation:
 - Sales of >200M
 - Gross margin >35%
 - EBIT margin >5%

Long-term

- + Continue revenue growth at positive EBIT and cash generation:
 - Sales of >200M
 - Gross margin >35%
 - EBIT margin 10%

Market Outlook

- + Market environment becomes challenging in 1H 2016 and customers become more cautious with investments
- + Outlook of SUSS MicroTec and our peer group is cautiously optimistic for H2 2016
- + Market analysts expect the semi market to grow by 1 - 2% in 2016
- + Market for WLP and assembly equipment expected to be flat
- + Market forecasts show a return to the growth path in WLP and assembly with double digit yoy growth in 2017 and 2018

SUSS MicroTec Outlook

- + FY 2016: Sales 170 - 180 € million
 EBIT 9 – 13 € million
- + Q1 2016: Order Intake 25 - 35 € million

A close-up photograph of a hand holding a black marker, writing the words "Thank you!" in a cursive script on a white surface. The background of the slide features a blue, textured pattern resembling a microchip or circuit board.

SÜSS MicroTec AG
Schleissheimer Str. 90
85748 Garching

www.SUSS.com

Contact

Franka Schielke

Tel.: +49 89-32007- 161

Fax.: +49 89-32007- 451

Email: franka.schielke@suss.com

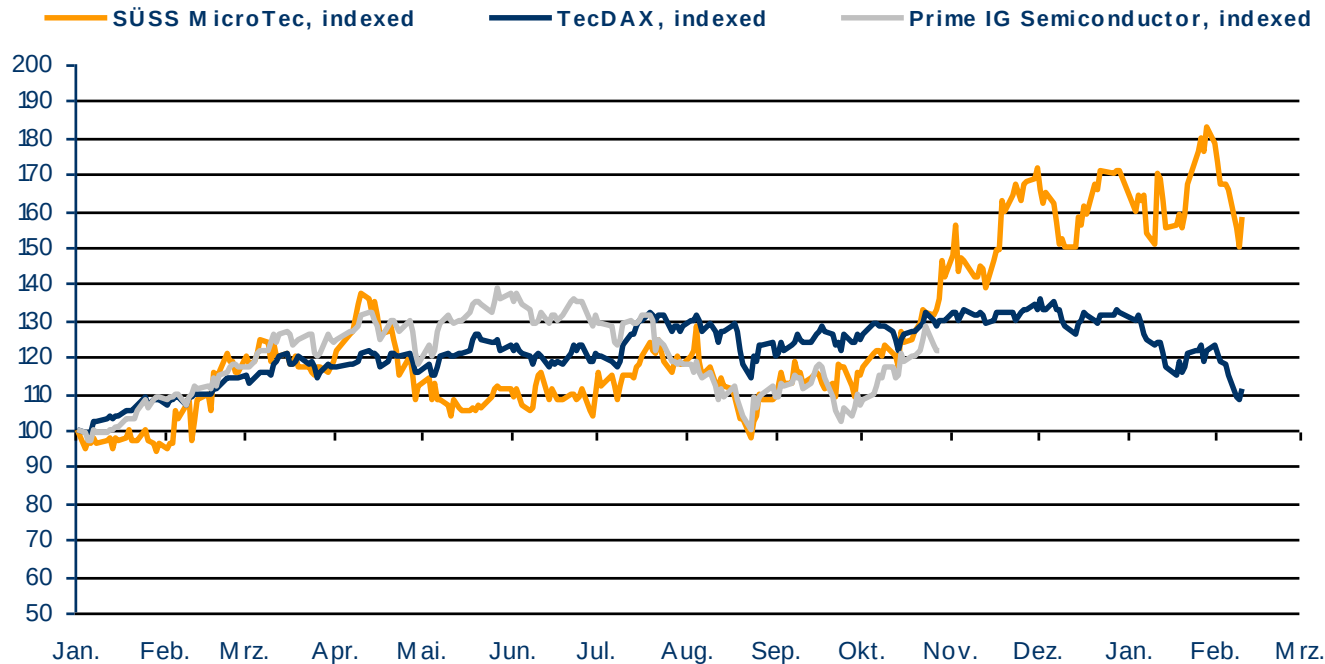
SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching
Germany
www.suss.com

Financial Calendar 2016

KeplerCheuvreux Investment Conference, Frankfurt	20 Jan
Annual Report 2015	30 Mar
Quarterly Report 2016	4 May
Annual General Meeting 2016, Munich	15 Jun
Interim Report 2016	5 Aug
Nine-month Report 2016	9 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2015: 4.88 €)



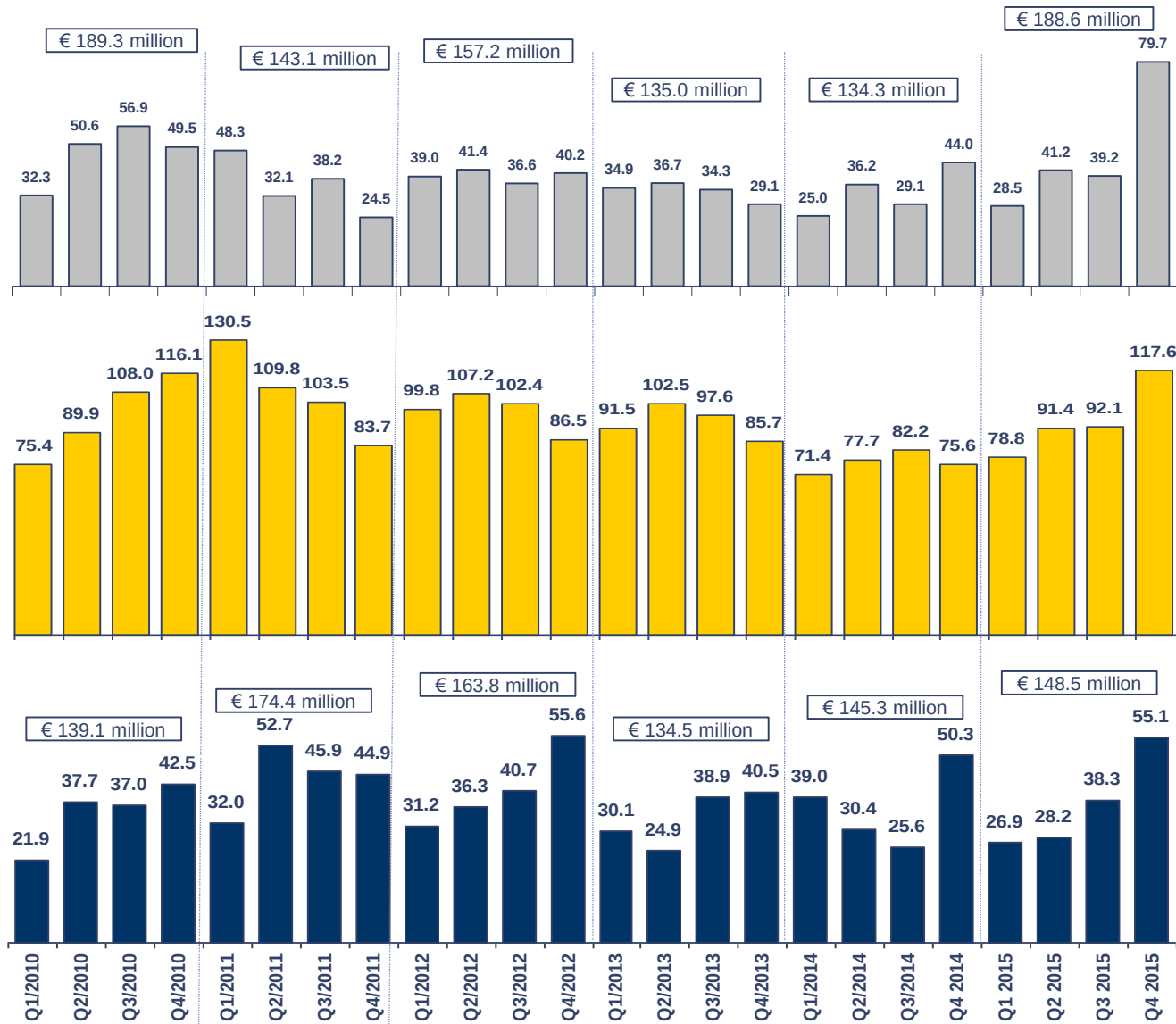
Major Shareholders:

Henderson	5.1%
Universal	4.86%
Sycomore	3.1%
INKA	3.1%
Baillie Gifford	3.0%

Average daily trading volume January 2015 – February 2016: ~ 135,000

Date	Institution	Analyst	Recommendation	Target
11.02.2016	Hauck & Aufhäuser	Tim Wunderlich	Buy	12,50 EUR
11.02.2016	Baader Bank AG	Günter Hollfelder	Buy	8,00 EUR
11.02.2016	Warburg Research	Malte Schaumann	Buy	12,00 EUR
04.12.2015	DZ Bank AG	Harald Schnitzer	Sell	7,50 EUR
11.02.2016	Kepler Cheuvreux	Bernd Laux	Hold	8,50 EUR
11.02.2016	Berenberg	Tammy Qiu	Buy	9,00 EUR
11.02.2016	equinet Bank AG	Adrian Pehl	Auccumulate	7,50 EUR
28.01.2016	Bankhaus Lampe	Dr. Karsten Iltgen	Hold	8,00 EUR
08.05.2015	Oddo Seydler	Veysel Taze	Buy	6,00 EUR
13.08.2014	Deutsche Bank	Uwe Schupp	Buy	9,00 EUR

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

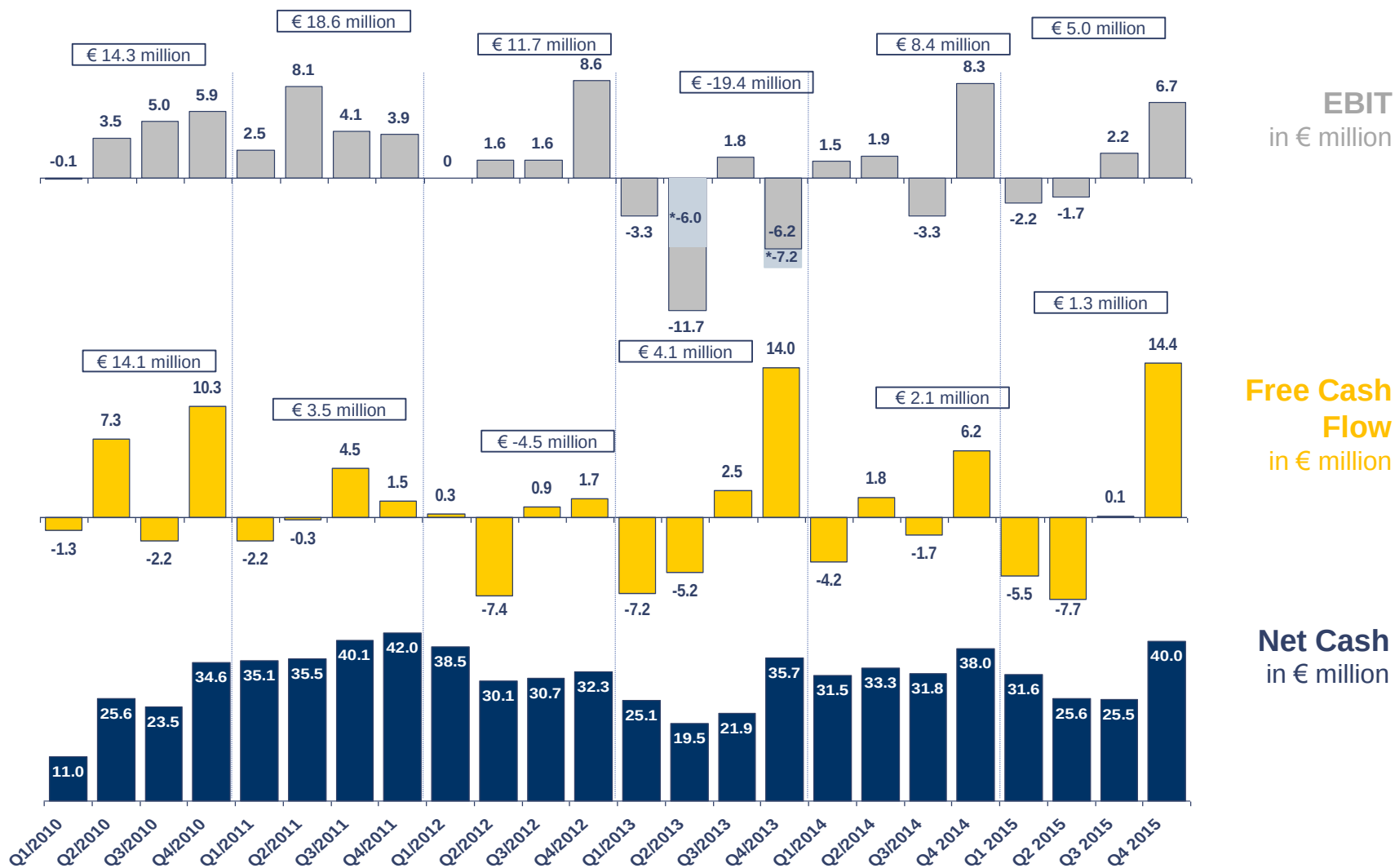


Order Entry
in € million

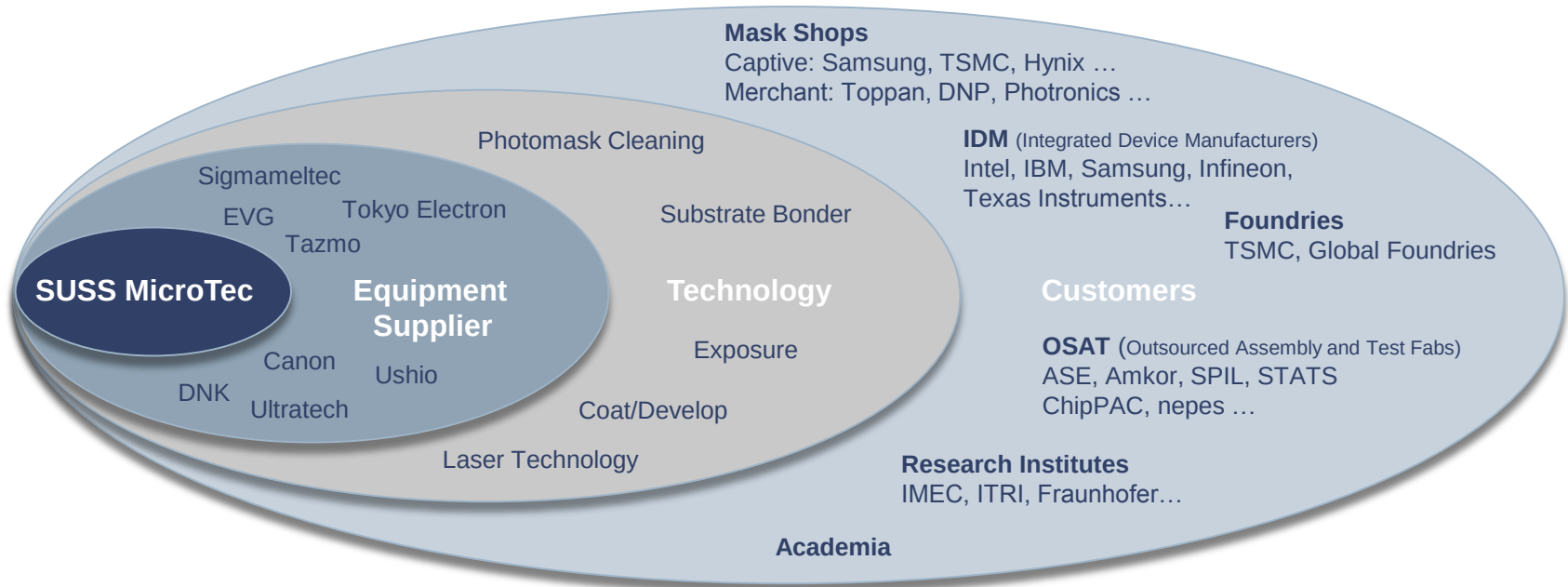
Order Backlog
in € million

Sales
in € million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



MAIN COMPETITORS AND PEER GROUP



Peer Group

BE Semiconductor:

equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy

Ultratech:

steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)

Kulicke & Soffa:

design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)

Rudolph Tech:

equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)

EV Group:

equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Production facility ~15,000 m²



Garching*

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Production facility ~9,000 m²



USA

Corona (California)

- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Production facility ~7,000 m²



*Production site is owned by SUSS MicroTec